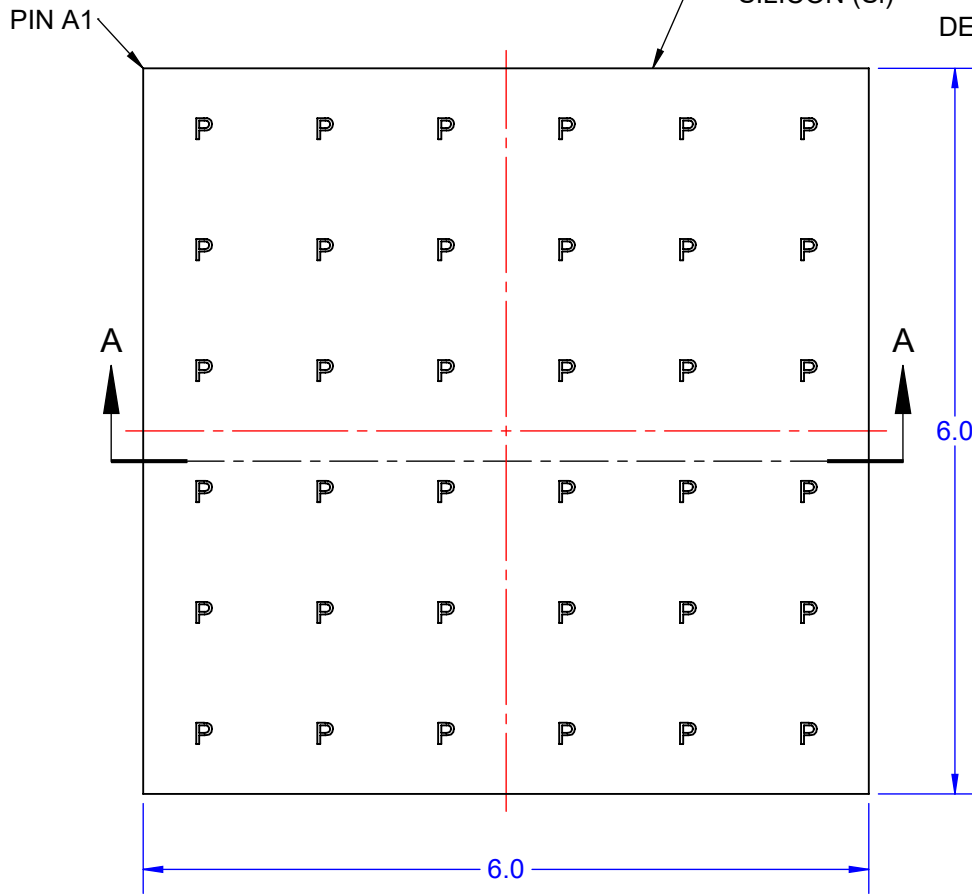
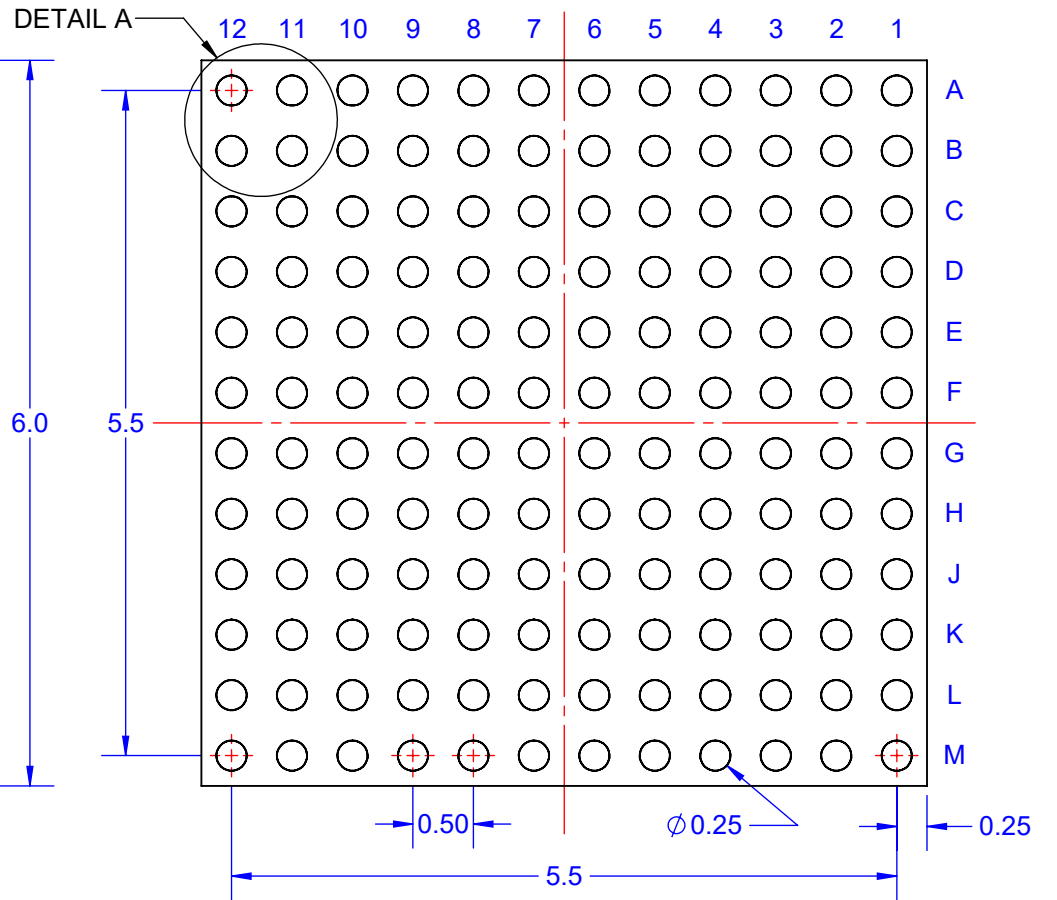


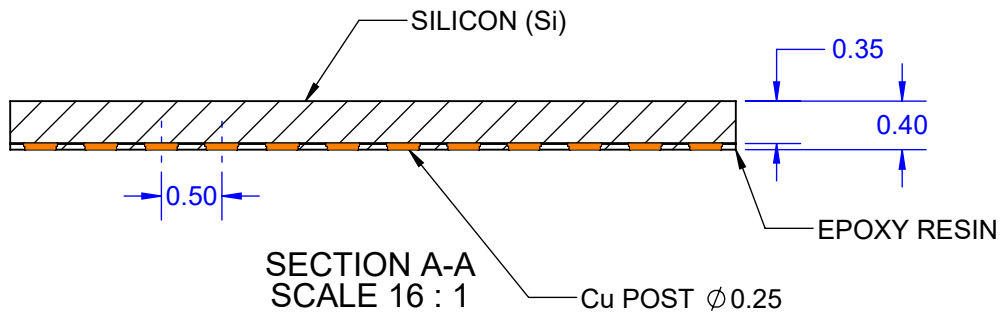
TOP VIEW



PAD VIEW



- Notes: (Unless Otherwise Specified).
- 1) ALL DIMENSIONS ARE IN MM.
 - 2) PAD ALLOY: Cu (50 μ m THICK).
 - 3) PAD Cu DIAMETER: $\phi 0.25$
 - 4) DIE MATERIAL: Si (SILICON).
 - 5) DAISY CHAIN PATTERN (SEE PAGE 2).

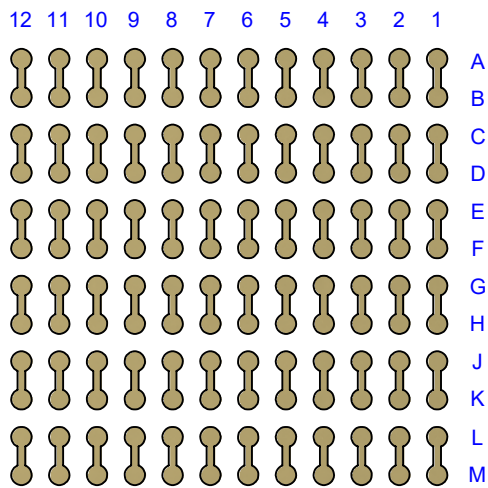


SECTION A-A
SCALE 16 : 1

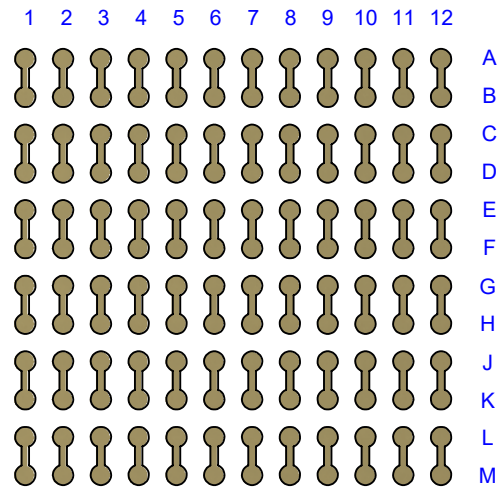
APPROVALS	DATE	TopLine [®]			
DRAWN T. Au	6/25/2021				
ENG M. Hart	6/25/2021	TITLE eWLP144T.5-DC127D 144-PAD P=0.5mm			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		16:1	A	751279	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 9
REVISED					

DAISY CHAIN PATTERN

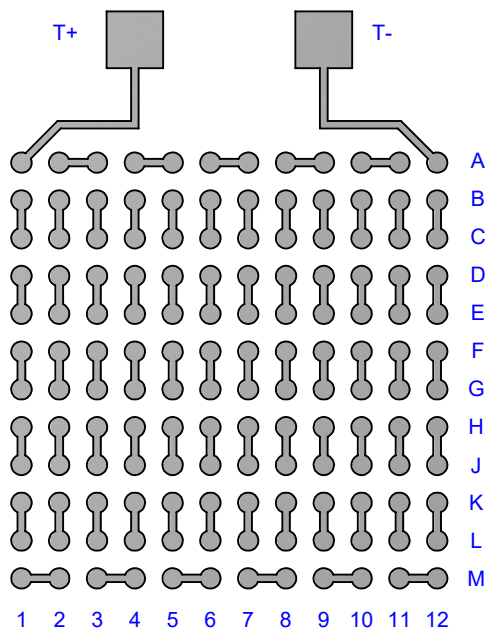
PAD VIEW



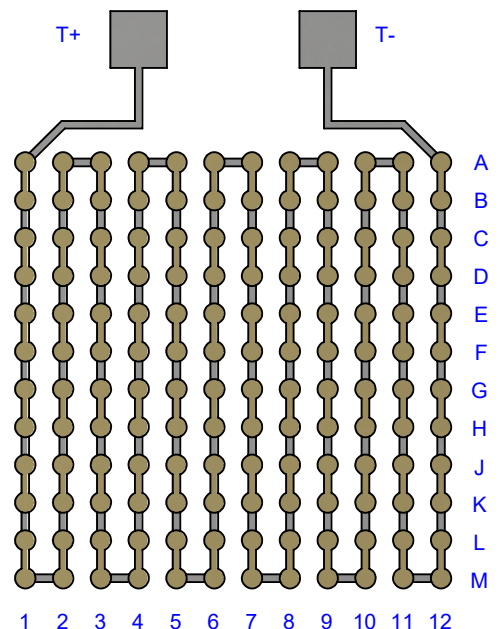
**BOTTOM SIDE
(TOP X-RAY VIEW)**



**TEST VEHICLE
BOARD**



**AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)**



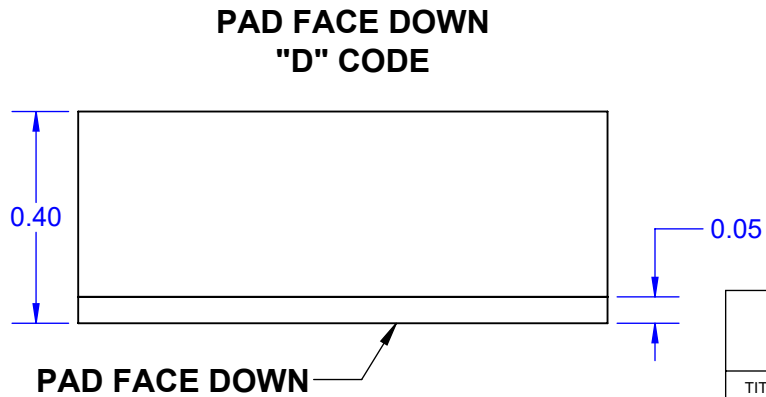
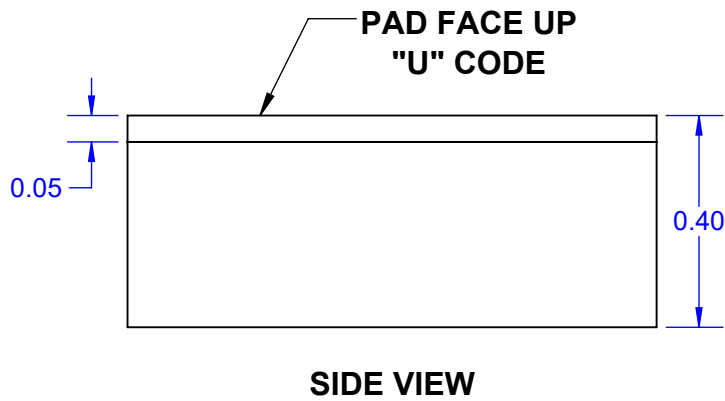
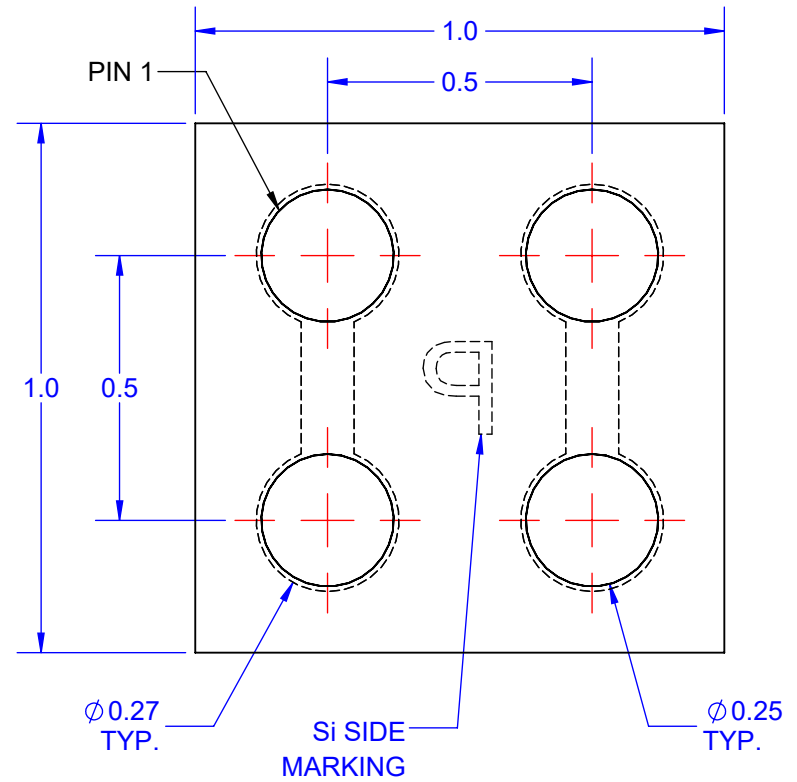
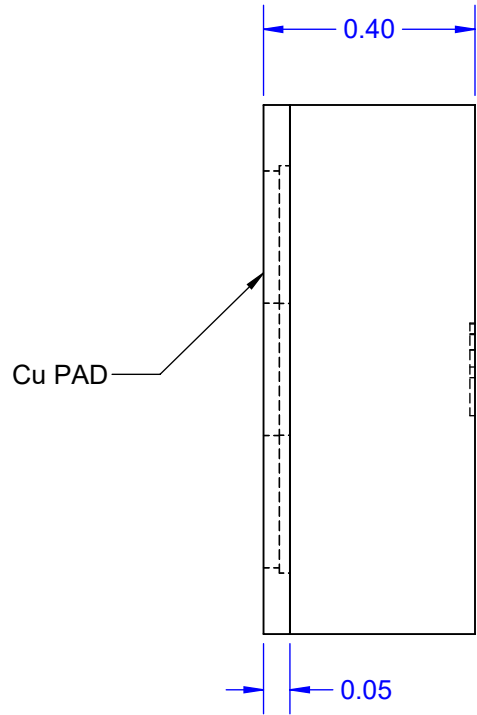
Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.
DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu PAD DIAMETER 0.25mm (9.8 mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.10mm (3.9 mil).

TopLine[®]			
TITLE		eWLP144T.5-DC127D 144-PAD P=0.5mm	
SCALE	SIZE	DRAWING NO.	REV
12:1	A	751279	A
DO NOT SCALE DRAWING			SHEET 2 OF 9

DETAIL A COPPER POST

COPPER PAD ROUND POST



TopLine

TITLE eWLP144T.5-DC127D
144-PAD P=0.5mm

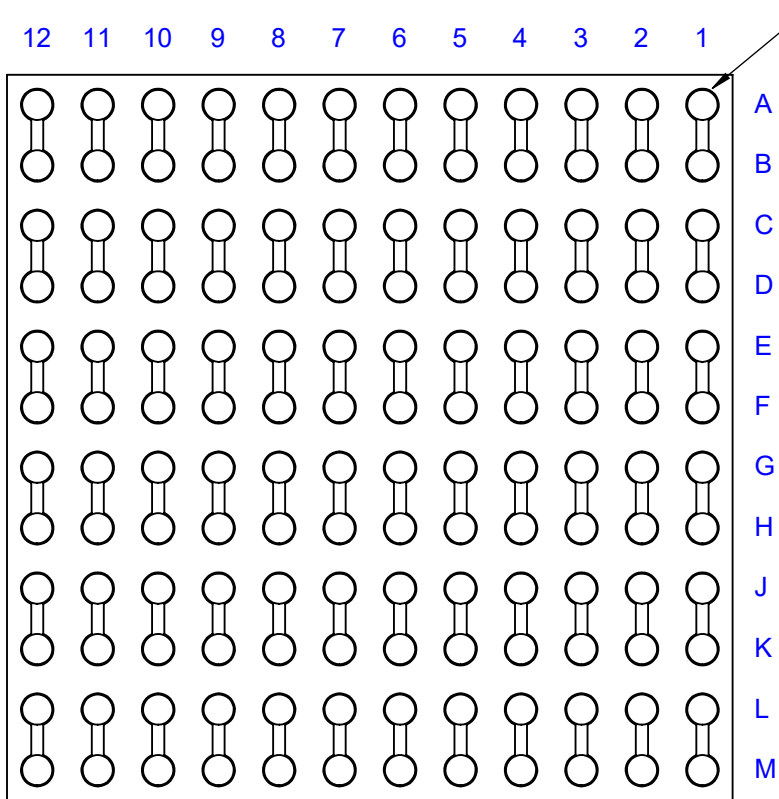
SCALE 70:1	SIZE A	DRAWING NO. 751279	REV A
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DO NOT SCALE DRAWING

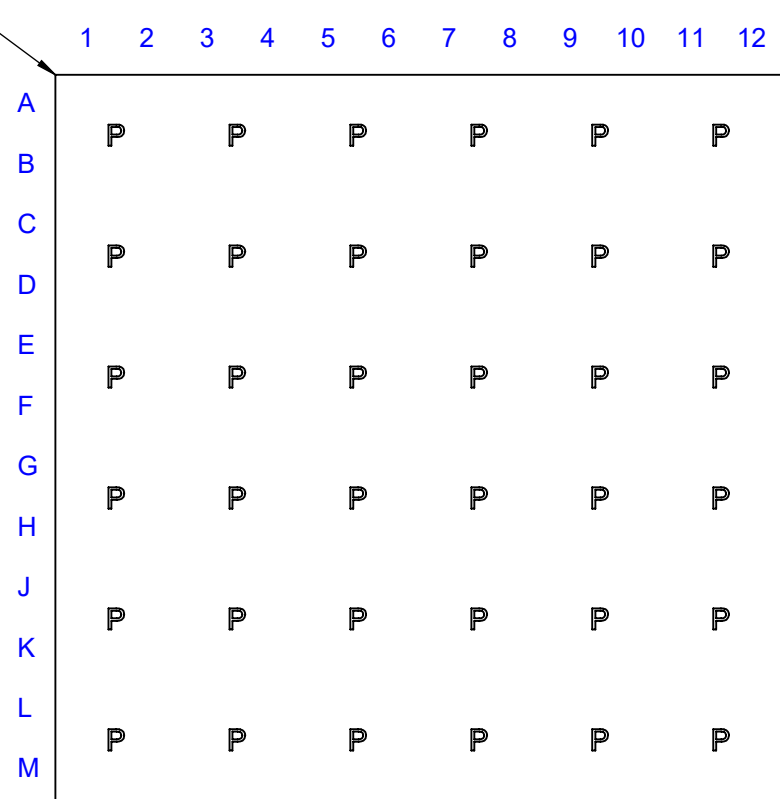
SHEET 3 OF 9

DAISY CHAIN PATTERN ROUND PADS

PAD VIEW



TOP MARKING



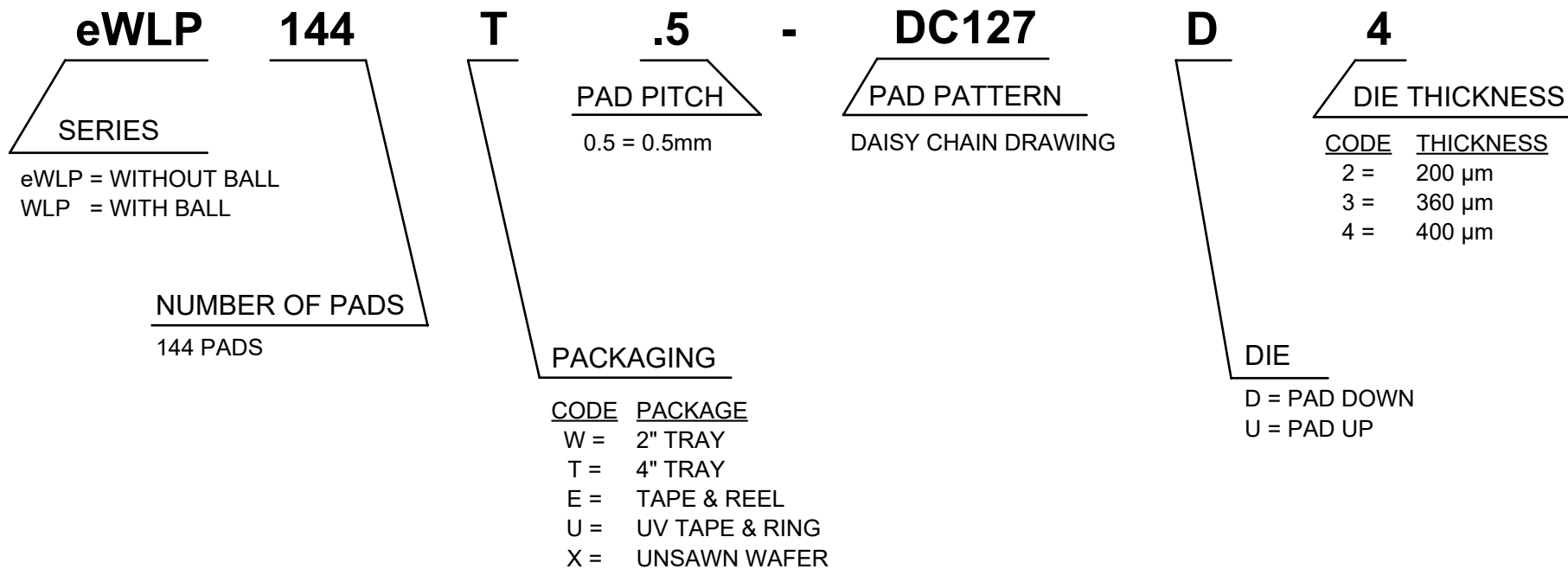
TopLine[®]

TITLE eWLP144T.5-DC127D
144-PAD P=0.5mm

SCALE 16:1	SIZE A	DRAWING NO. 751279	REV A
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DO NOT SCALE DRAWING SHEET 4 OF 9

PART NUMBERING SYSTEM



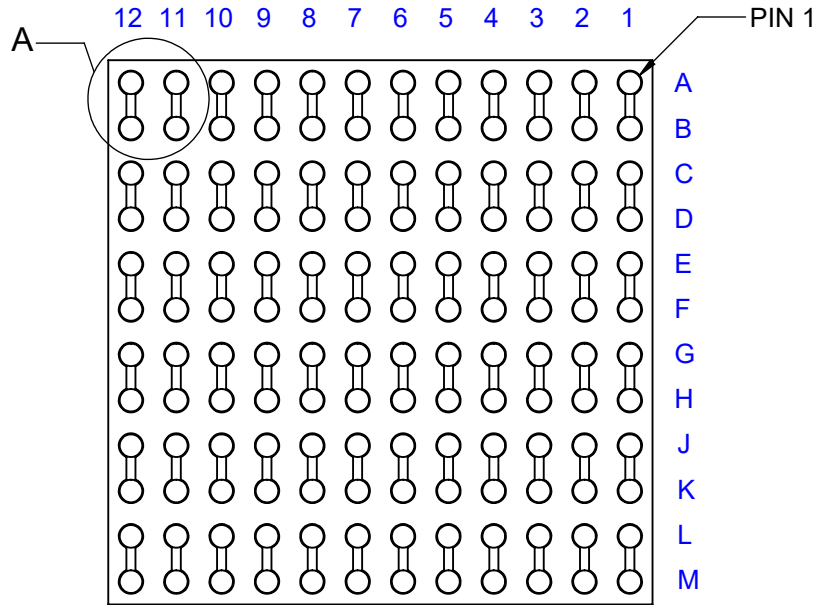
TopLine[®]			
TITLE eWLP144T.5-DC127D 144-PAD P=0.5mm			
SCALE NONE	SIZE A	DRAWING NO. 751279	REV A
DO NOT SCALE DRAWING		SHEET 5 OF 9	

DWG	PART NUMBER	DIE THICKNESS	PAD PIN 1	PAD UP/DOWN	PACKAGING
ROUND PADS					
651277	eWLP144W.5-DC127U2	200 µm	ROUND	UP	2-INCH TRAY
651278	eWLP144W.5-DC127D2	200 µm	ROUND	DOWN	2-INCH TRAY
651279	eWLP144T.5-DC127U2	200 µm	ROUND	UP	4-INCH TRAY
651270	eWLP144T.5-DC127D2	200 µm	ROUND	DOWN	4-INCH TRAY
651271	eWLP144E.5-DC127D2	200 µm	ROUND	DOWN	TAPE & REEL
651272	eWLP144E.5-DC127D2	200 µm	ROUND	DOWN	CUT TAPE
651273	eWLP144U.5-DC127U2	200 µm	ROUND	UP	SAWN WAFER - UV TAPE & RING
651275	eWLP144X.5-DC127U2	200 µm	ROUND	UP	UNSAWN WAFER

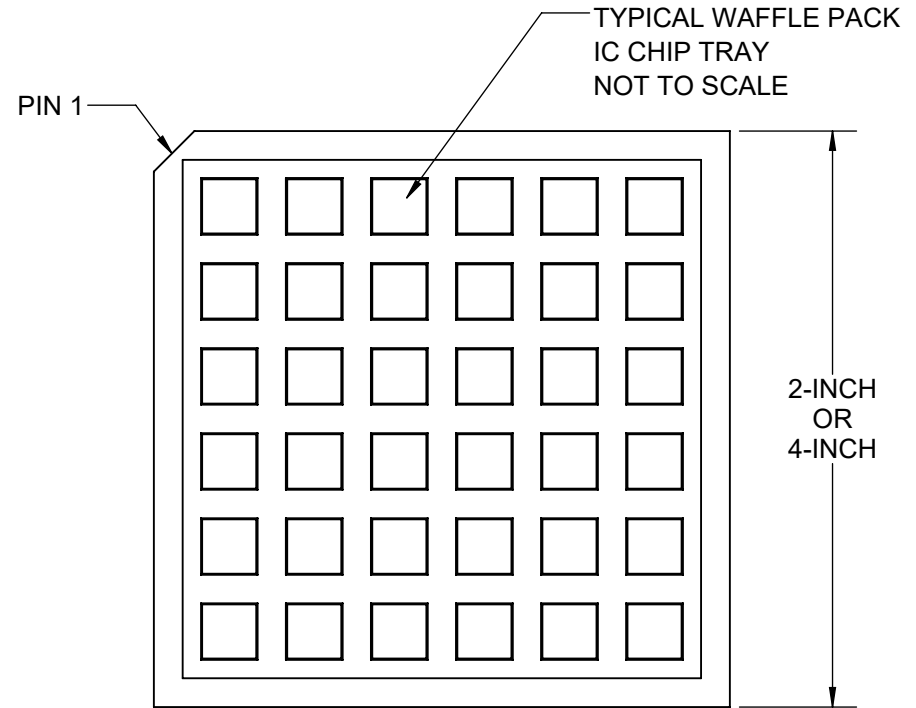
DWG	PART NUMBER	DIE THICKNESS	PAD PIN 1	PAD UP/DOWN	PACKAGING
ROUND PADS					
751277	eWLP144W.5-DC127U4	400 µm	ROUND	UP	2-INCH TRAY
751278	eWLP144W.5-DC127D4	400 µm	ROUND	DOWN	2-INCH TRAY
751279	eWLP144T.5-DC127U4	400 µm	ROUND	UP	4-INCH TRAY
751270	eWLP144T.5-DC127D4	400 µm	ROUND	DOWN	4-INCH TRAY
751271	eWLP144E.5-DC127D4	400 µm	ROUND	DOWN	TAPE & REEL
751272	eWLP144E.5-DC127D4	400 µm	ROUND	DOWN	CUT TAPE
751273	eWLP144U.5-DC127U4	400 µm	ROUND	UP	SAWN WAFER - UV TAPE & RING
751275	eWLP144X.5-DC127U4	400 µm	ROUND	UP	UNSAWN WAFER

TopLine[®]			
TITLE		eWLP144T.5-DC127D 144-PAD P=0.5mm	
SCALE	SIZE	DRAWING NO.	REV
NONE	A	751279	A
DO NOT SCALE DRAWING			SHEET 6 OF 9

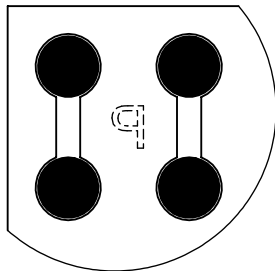
**DAISY CHAIN
PAD VIEW**



**WAFFLE PACK
PAD SIDE FACE UP**



NUMBER OF POCKETS WILL CHANGE
BASED ON THE SIZE OF THE CHIP



DETAIL A
SCALE 32:1
ROUND PAD

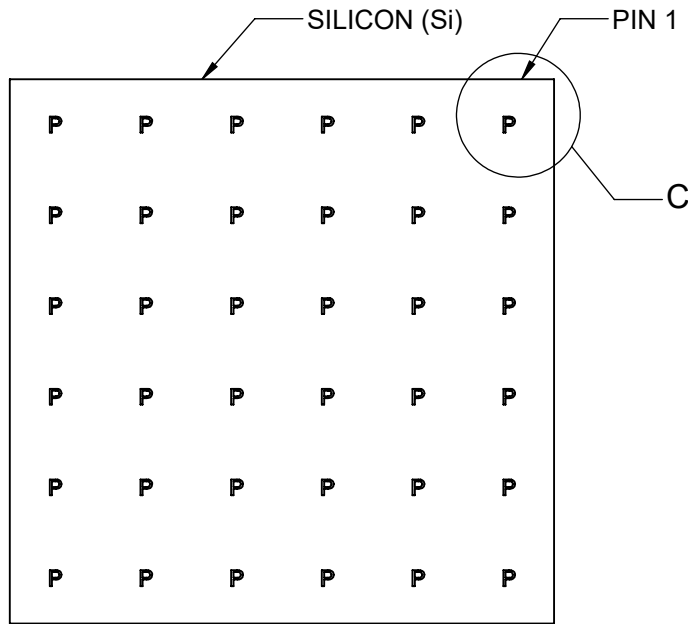
Notes: (Unless Otherwise Specified).

- 1) TOP SIDE LASER MARKING.
- 2) ORIENT LETTERS FOR LOCATION OF PIN A1 CORNER.
- 3) ALLOWABLE LETTER MARKING: A, F, T, M, L, Y AND P.
- 4) SINGLE LETTER IS REPEATED MULTIPLE TIMES ACROSS TOP SIDE.
- 5) DAISY CHAIN IS HIDDEN UNDER RESIN ON PAD SIDE.
- 6) TOP SIDE DOES NOT HAVE A DOT FOR LOCATION OF PIN A1.
- 7) LETTERS ARE NOT MARKED ON BOTTOM (PADS) SIDE.

MARKING CODE	
PITCH	LETTER
0.3 MM	A
0.4 MM	F
0.5 MM	P

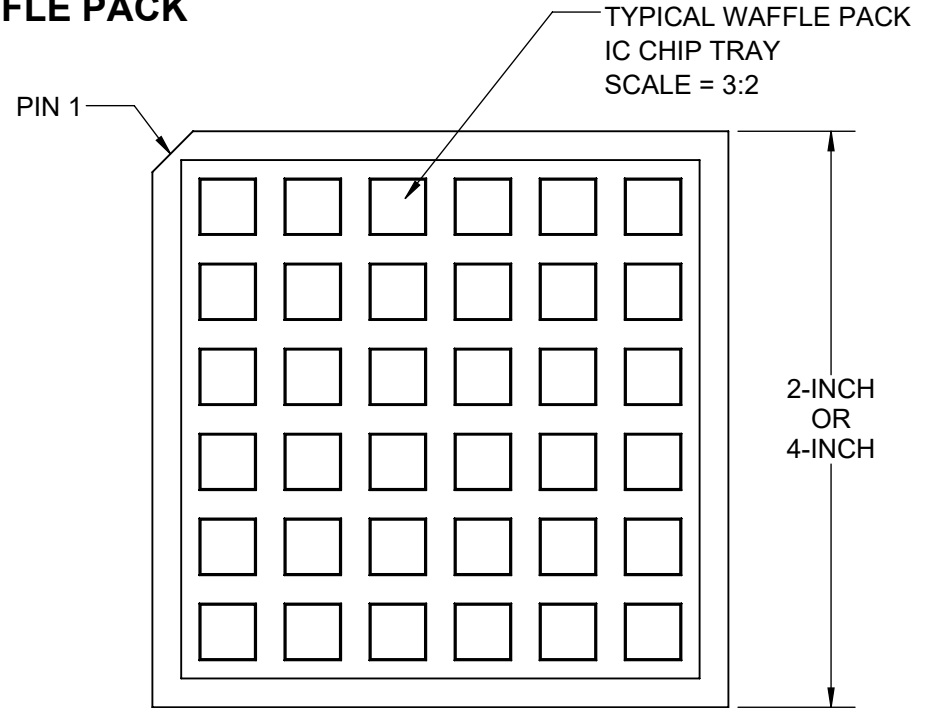
TopLine®			
TITLE eWLP144T.5-DC127D 144-PAD P=0.5mm			
SCALE 12:1	SIZE A	DRAWING NO. 751279	REV A
DO NOT SCALE DRAWING			SHEET 7 OF 9

TOP VIEW



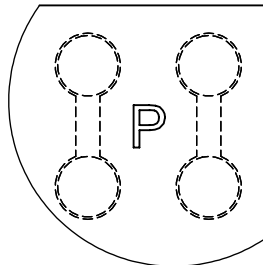
EXAMPLE OF ORIENTATION OF MARKINGS ON eWLP

PAD SIDE DOWN ORIENTATION WAFFLE PACK



NUMBER OF POCKETS WILL CHANGE BASED ON THE SIZE OF THE WLP CHIP

DAISY CHAIN VIEWED THRU DIE



DAISY CHAIN ORIENTATION

DETAIL C SCALE 32 : 1 ROUND PAD

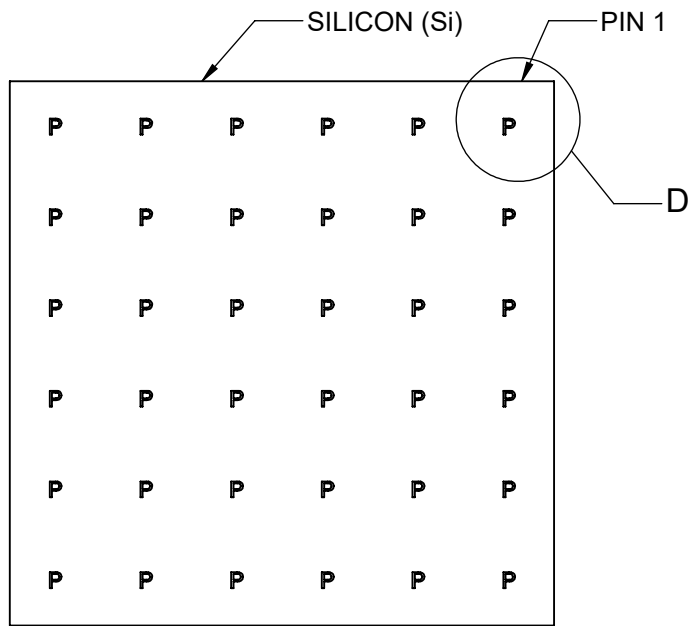
Notes: (Unless Otherwise Specified).

- 1) EXAMPLE OF TOP SIDE LASER MARKING.
- 2) ORIENT LETTERS FOR LOCATION OF PIN A1 CORNER.
- 3) ALLOWABLE LETTER MARKING: A, F, T, M, L, Y AND P.
- 4) SINGLE LETTER IS REPEATED MULTIPLE TIMES ACROSS TOP SIDE.
- 5) DAISY CHAIN IS HIDDEN UNDER RESIN ON PAD SIDE.
- 6) TOP SIDE DOES NOT HAVE A DOT FOR LOCATION OF PIN A1.
- 7) LETTERS ARE NOT MARKED ON BOTTOM (PADS) SIDE.

MARKING CODE	
PITCH	LETTER
0.3 MM	A
0.4 MM	F
0.5 MM	P

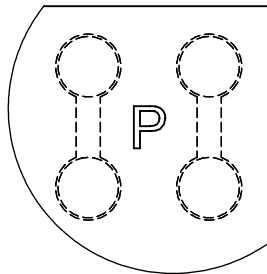
TopLine[®]			
TITLE eWLP144T.5-DC127D 144-PAD P=0.5mm			
SCALE 12:1	SIZE A	DRAWING NO. 751279	REV A
DO NOT SCALE DRAWING		SHEET 8 OF 9	

TOP VIEW



EXAMPLE OF ORIENTATION OF MARKINGS ON eWLP

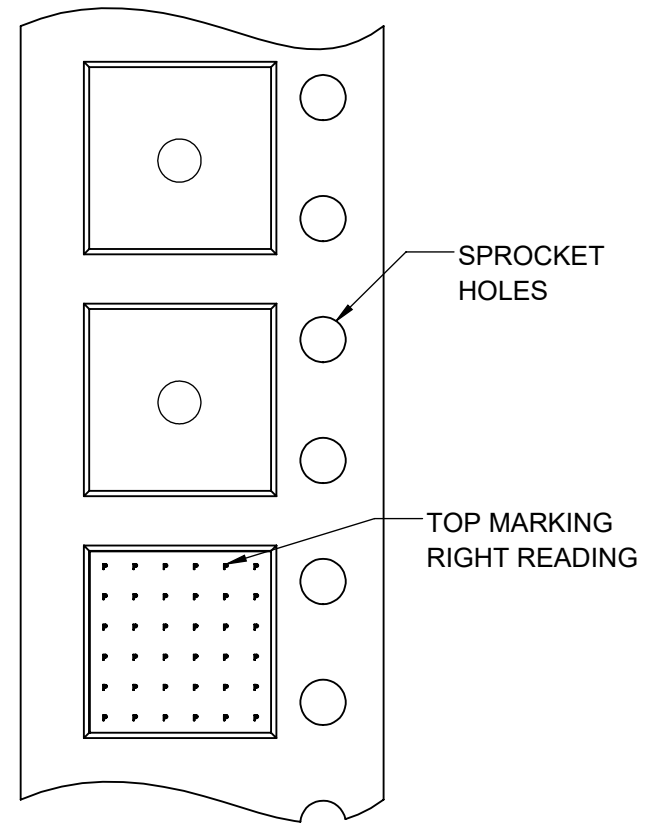
DAISY CHAIN VIEWED THRU DIE



DAISY CHAIN ORIENTATION

DETAIL D NOT TO SCALE ROUND PAD

eWLP ORIENTATION TAPE AND REEL



DIRECTION OF FEED

Notes: (Unless Otherwise Specified).

- 1) TOP SIDE LASER MARKING.
- 2) ORIENT LETTERS FOR LOCATION OF PIN A1 CORNER.
- 3) ALLOWABLE LETTER MARKING: A, F, T, M, L, Y AND P.
- 4) SINGLE LETTER IS REPEATED MULTIPLE TIMES ACROSS TOP SIDE.
- 5) DAISY CHAIN IS HIDDEN UNDER RESIN ON PAD SIDE.
- 6) TOP SIDE DOES NOT HAVE A DOT FOR LOCATION OF PIN A1.
- 7) LETTERS ARE NOT MARKED ON BOTTOM (PADS) SIDE.

MARKING CODE	
PITCH	LETTER
0.3 MM	A
0.4 MM	F
0.5 MM	P

TopLine[®]			
TITLE eWLP144T.5-DC127D 144-PAD P=0.5mm			
SCALE 12:1	SIZE A	DRAWING NO. 751279	REV A
DO NOT SCALE DRAWING			SHEET 9 OF 9